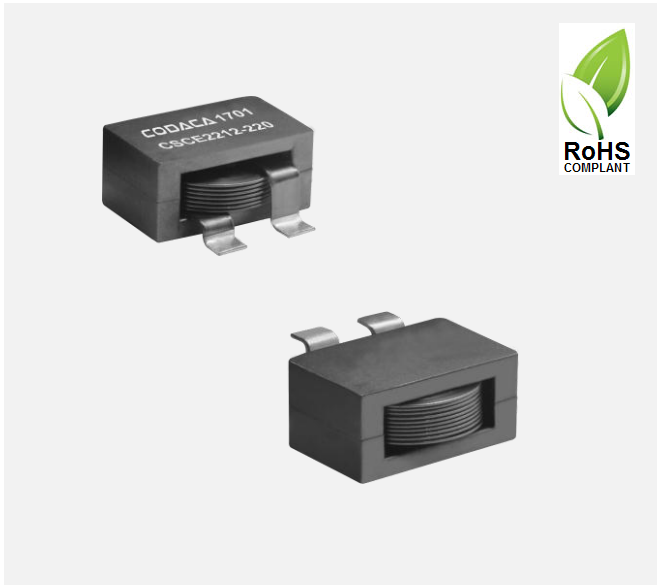
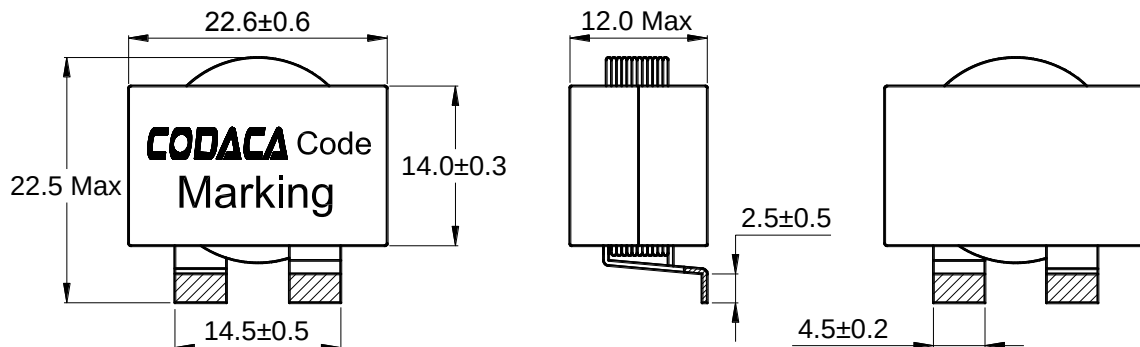




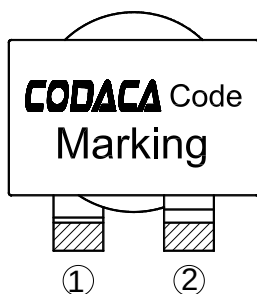
Outline: 产品概要

- Assemblage design, sturdy structure.
组立式设计，结构坚固。
- Small volume, high current, low magnetic loss, low ESR, small parasitic capacitance.
小体积，大电流，低磁损，低阻抗，寄生电容小。
- Closed magnetic circuit, ultra low buzz noise.
磁路闭合，超低蜂鸣噪音。
- Temperature rise current and saturation current is less influenced by environment.
温升电流及饱和电流受环境条件影响小。
- Operating temperature : $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$
(Including coil's temperature rise)
工作温度： $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (包含线圈发热)

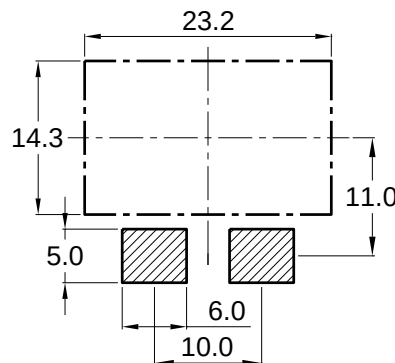
1 Appearance and dimensions (mm) 外形尺寸



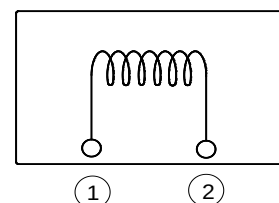
2 Marking 印字标识



3 Reference land pattern (mm) 参考基板尺寸



4 Schematic 原理图

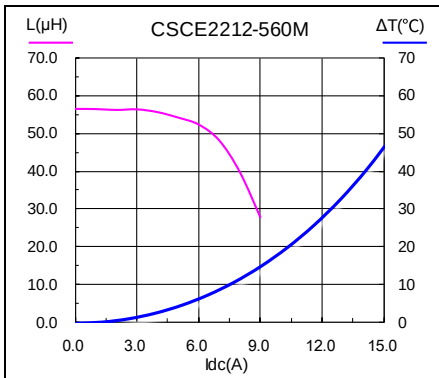
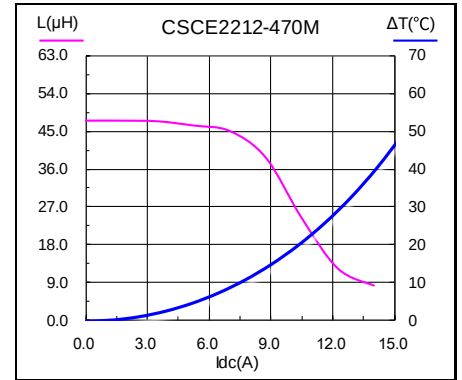
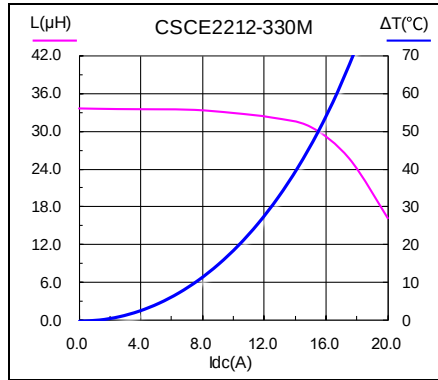
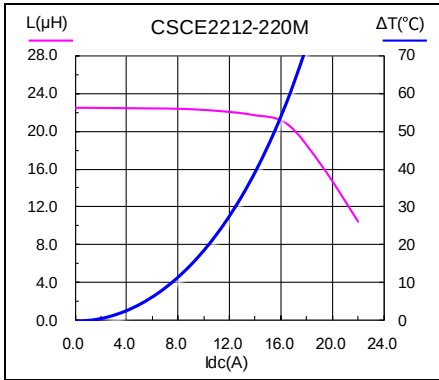
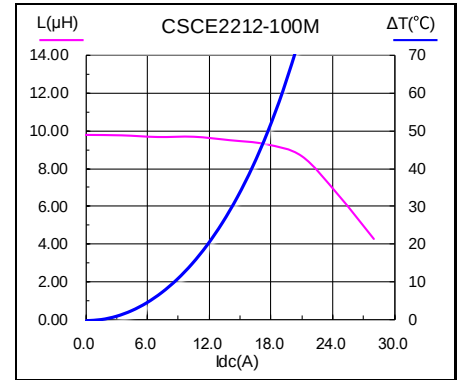
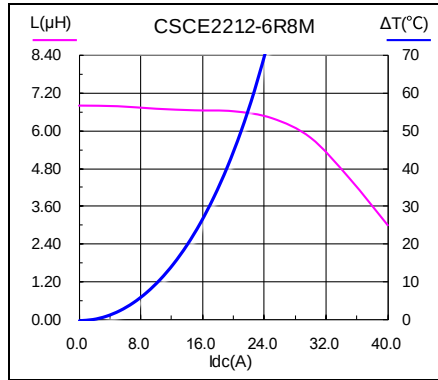
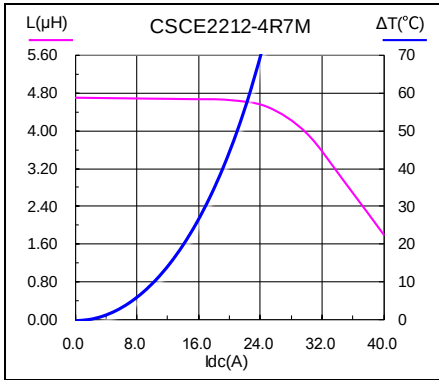
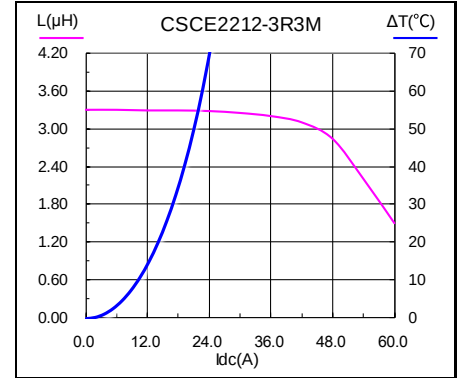
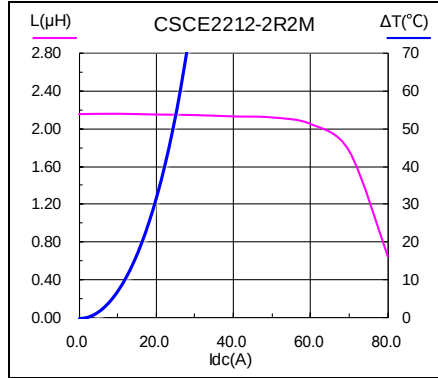
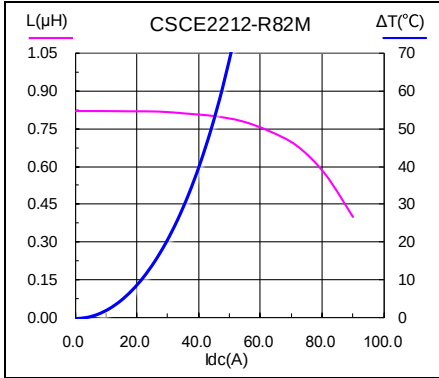


5 Electrical characteristics
电气特性

Part No. 型号	Inductance (μH) 电感值 ※1 ±20%	D.C.R. (mΩ) 直流电阻		Saturation current (A) 饱和电流 ※2 Typical	Temperature rise current (A) 温升电流 ※3 Typical
		Typical	Max		
CSCE2212-R82M	0.82	0.57	0.62	70.0	40.0
CSCE2212-2R2M	2.20	2.68	2.98	64.0	22.0
CSCE2212-3R3M	3.30	4.30	4.80	49.0	19.0
CSCE2212-4R7M	4.70	4.30	4.80	33.0	19.0
CSCE2212-6R8M	6.80	4.30	4.80	29.0	19.0
CSCE2212-100M	10.0	4.60	5.20	20.0	16.0
CSCE2212-220M	22.0	12.7	14.0	15.0	13.0
CSCE2212-330M	33.0	12.7	14.0	10.5	13.0
CSCE2212-470M	47.0	12.7	14.0	8.00	13.0
CSCE2212-560M	56.0	12.7	14.0	5.00	13.0

- All data is tested based on 25°C ambient temperature.
所有数据基于环境温度 25°C条件下测试。
- ※1 Inductance measure condition at 100kHz, 0.1V.
电感测试条件为 100kHz, 0.1V。
- ※2 Saturation current: the actual value of DC current when the inductance decrease 20% of its initial value.
饱和电流: 电感值下降其初始值的 20%时所加载的实际直流电流值。
- ※3 Temperature rise current: the actual value of DC current when the temperature rise is ΔT40°C(Ta=25°C).
温升电流: 使产品温度上升到 ΔT40°C时所加载的实际直流电流值(Ta=25°C)。
- ※ Special remind: Circuit design, component placement, PWB size and thickness, cooling system and etc.
all will affect the product temperature. Please verify the product temperature in the final application.
特别提醒: 线路设计, 组件布局, 印刷线路板(PWB)尺寸及厚度, 散热系统等均会影响产品温度。
请务必在最终应用时, 验证产品发热状况。

6 Saturation current VS temperature rise current curve 饱和电流 VS 温升电流曲线

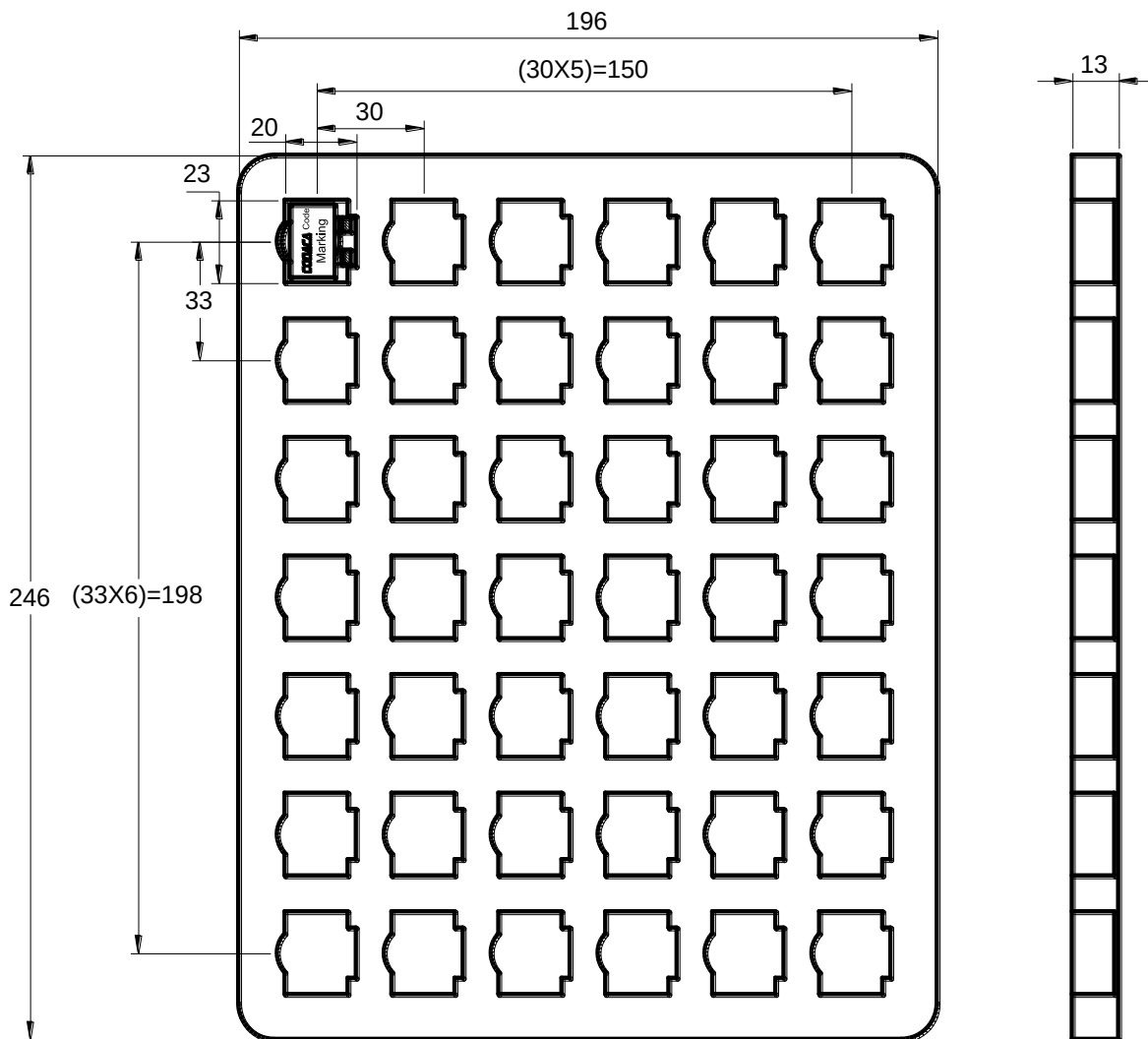


7 Packing specification

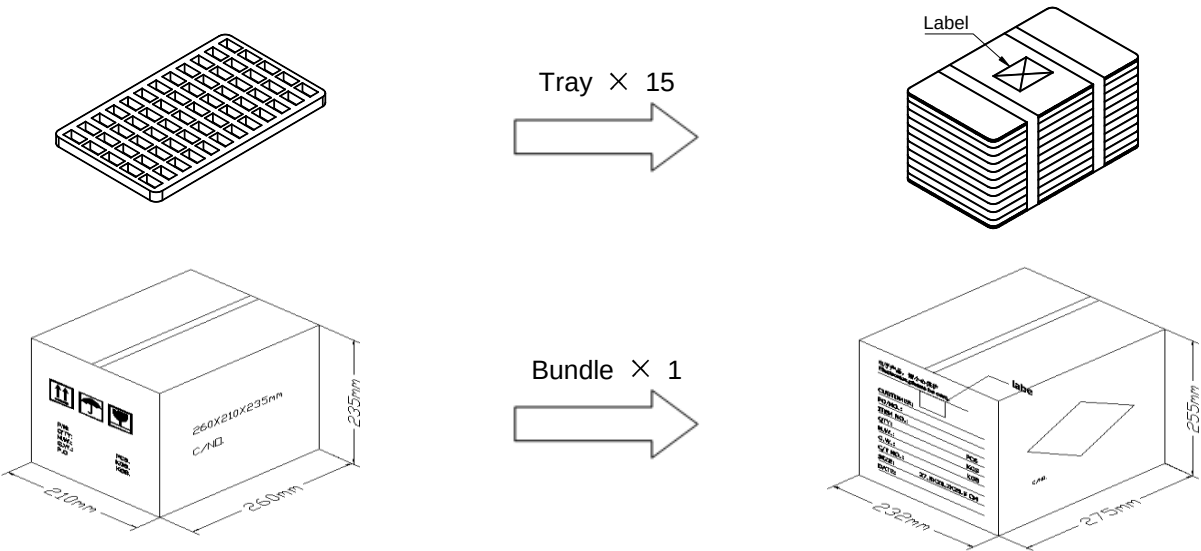
包装规格

7.1 Plastic tray dimensions (mm)

吸塑盘尺寸



7.2 Packing
包装



7.3 Carton dimensions and packing quantity
包装箱尺寸和包装数量

■ Inner Carton : 260×210×235mm
内包装箱

■ Out Carton : 275×232×255mm
外包装箱

Product Series 产品系列	Quantity / Tray 数量 / 盘	Quantity / Bundle 数量 / 捆	Out Carton Quantity 外箱 包装总数量
CSCE2212	42pcs	(42×15) = 630pcs	(630×1) = 630pcs

7.4 Label making
标签标识

The following items will be marked on the tray of product label and shipping label.
以下项目将明确标识于产品吸塑盘标签以及运输标签上。

Production Label
产品标签

- Part No.
产品型号
- Electrical Information
产品电性信息
- Quantity
数量
- Packing No.
包装流水号

Shipping Label
运输标签

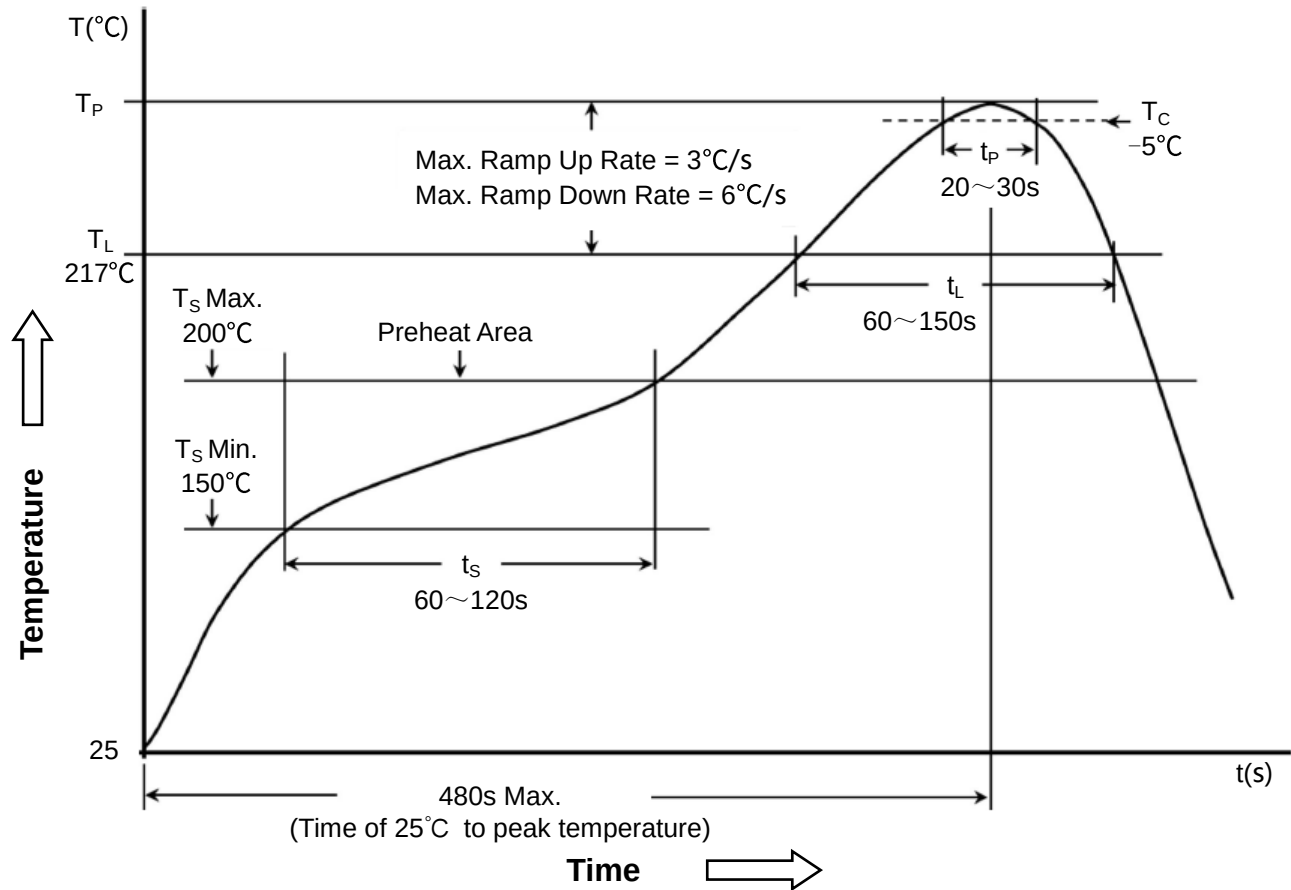
- Customer Name
客户名称
- Customer Part No.
客户型号
- Supplier Part No.
供应商型号
- Supplier Name
供应商名称
- Country of origin
产品产地

8 Soldering specification

焊接规格

8.1 Reflow profile for SMT components

SMT 回流焊温度曲线



8.2 Classification of peak package body temperature (T_{P})

封装体峰值温度(T_{P})分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm ³	350~2000 mm ³	>2000 mm ³
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.
回流焊参照标准 IPC/JEDEC J-STD-020D。